



Material Content Data Sheet



Sales Product Name				SAK-C164CI-L25M CA+		Issued		29. August 2013	
MA#				MA001097108					
Package				PG-MQFP-80-7		Weight*		974.39 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	20.746	2.13	2.13	21291	21291	
leadframe	non noble metal	magnesium	7439-95-4	0.349	0.04		358		
	inorganic material	silicon	7440-21-3	1.511	0.16		1551		
	non noble metal	nickel	7440-02-0	6.975	0.72		7158		
	non noble metal	copper	7440-50-8	223.668	22.95	23.87	229547	238614	
wire	noble metal	gold	7440-57-5	3.369	0.35	0.35	3457	3457	
encapsulation	organic material	carbon black	1333-86-4	2.099	0.22		2155		
	plastics	epoxy resin	-	88.878	9.12		91214		
	inorganic material	silicondioxide	60676-86-0	608.848	62.48	71.82	624852	718221	
leadfinish	non noble metal	tin	7440-31-5	9.487	0.97	0.97	9736	9736	
plating	noble metal	silver	7440-22-4	3.927	0.40	0.40	4030	4030	
glue	plastics	acrylic resin	-	0.906	0.09		930		
	noble metal	silver	7440-22-4	3.626	0.37	0.46	3721	4651	
*deviation	< 10%			Sum in total:		100,00		1000000	

Important Remarks:

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